

REFERENCE

SPEC. No. ED-05G041
ISSUE March 22, 2005

SHARP

OPTO-ELECTRONIC DEVICES DIVISION
ELECTRONIC COMPONENTS GROUP
SHARP CORPORATION

SPECIFICATION

DEVICE SPECIFICATION FOR

OPIC LIGHT DETECTOR

MODEL No.

IS471FE

Specified for _____

Enclosed please find copies of the Specifications which consists of 12 pages including cover.
After confirmation of the contents, please be sure to send back copy of the Specifications
with approving signature on each.

CUSTOMER'S APPROVAL

DATE

BY

PRESENTED

DATE

BY

H. O

H. Ogura,
Department General Manager of
Engineering Dept., III
Opto-Electronic Devices Div.
ELECOM Group
SHARP CORPORATION

REFERENCE

Product name : OPIC LIGHT DETECTOR

Model No. : IS471FE

1. These specification sheets include materials protected under copyright of Sharp Corporation ("Sharp"). Please do not reproduce or cause anyone to reproduce them without Sharp's consent.
2. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets, as well as the precautions mentioned below. Sharp assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets, and the precautions mentioned below.

(Precautions)

- (1) This product is designed for use in the following application areas ;

[· OA equipment · Audio visual equipment · Home appliances
· Telecommunication equipment (Terminal) · Measuring equipment
· Tooling machines · Computers (etc.)]-1✓

If the use of the product in the above application areas is for equipment listed in paragraphs (2) or (3), please be sure to observe the precautions given in those respective paragraphs.

- (2) Appropriate measures, such as fail-safe design and redundant design considering the safety design of the overall system and equipment, should be taken to ensure reliability and safety when this product is used for equipment which demands high reliability and safety in function and precision, such as ;

[· Transportation control and safety equipment (aircraft, train, automobile etc.)
· Traffic signals · Gas leakage sensor breakers · Rescue and security equipment
· Other safety equipment]

- (3) Please do not use this product for equipment which require extremely high reliability and safety in function and precision, such as ;

[· Space equipment · Telecommunication equipment (for trunk lines)
· Nuclear power control equipment · Medical equipment]

- (4) Please contact and consult with a Sharp sales representative if there are any questions regarding interpretation of the above three paragraphs.

3. Please contact and consult with a Sharp sales representative for any questions about this product.

REFERENCE

1. Application

This specification applies to the outline and characteristics of OPIC light detecting device; Model No. IS471FE.

2. Outline

Refer to the attached drawing No. : CY12969L02, page 3.

3. Ratings and characteristics

Refer to the attached sheet, page 4 to 7.

4. Reliability

Refer to the attached sheet, page 8.

5. Outgoing inspection

Refer to the attached sheet, page 9.

6. Supplement

(6-1) Equivalent circuit and Operating refer to the attached sheet, page 10.

(6-2) Packing refer to the attached sheet, page 11.

(6-3) This product is not designed against electromagnetic and ionized-particle irradiation.

(6-4) This product shall not contain the following materials.

Also, the following materials shall not be used in the production process for this product.

Materials for ODS : CFCs, Halon, Carbon tetrachloride, 1,1,1-Trichloroethane (Methyl chloroform)

(6-5) This product and packaging material shall not contain lead material.

(6-6) Product mass (Piece): Approximately 0.18g

7. Notes

(7-1) By-pass capacitor

To avoid the malfunction by the power line noise, please place the capacitor above $0.33\mu\text{F}$ ($f=1\text{MHz}$) between Vcc-GND (①-③ terminals).

(7-2) Cleaning conditions :

Solvent cleaning : Solvent temperature 45°C or less Immersion for 3 min or less

Ultrasonic cleaning : The effect to device by ultrasonic cleaning differs by cleaning bath size, ultrasonic power output, cleaning time, PCB size or device mounting condition etc.

Please test it in actual using condition and confirm that doesn't occur any defect before starting the ultrasonic cleaning.

The cleaning shall be carried out with solvent below.

Solvent : Ethyl alcohol, Methyl alcohol, Isopropyl alcohol

(7-3) Soldering

The lead pins should be soldered according to the absolute maximum ratings.

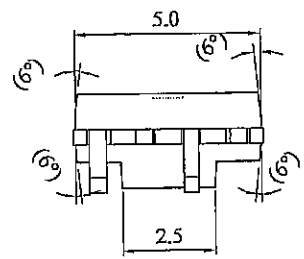
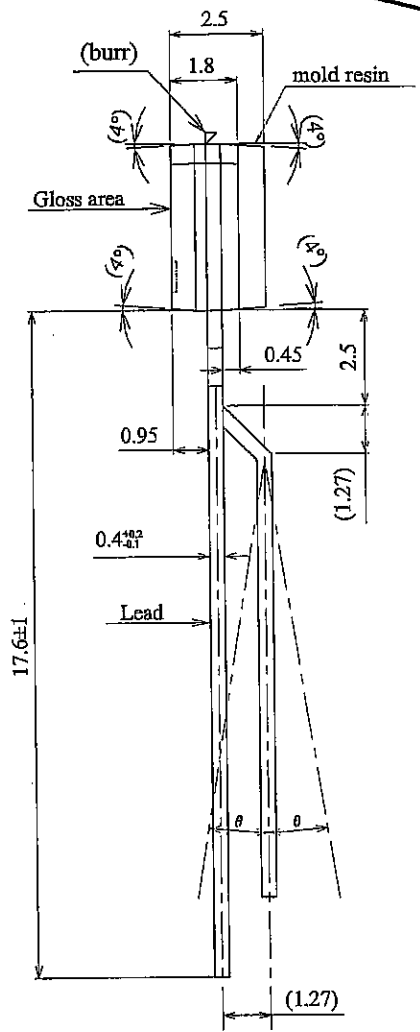
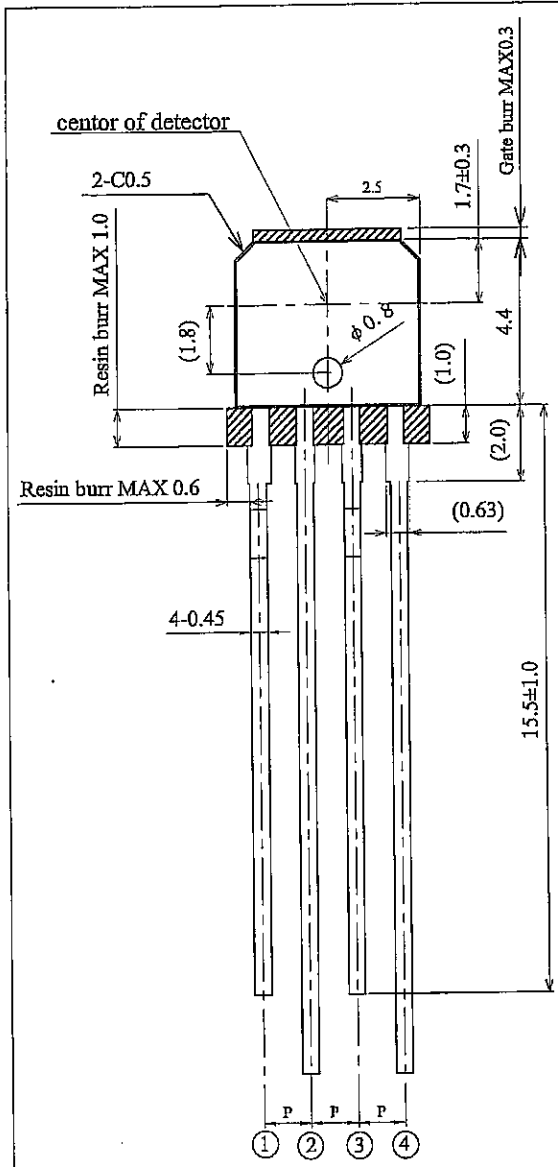
While or after soldering, the lead pins shall be free from external force.

This device shall not be soldered with preheat or reflow.

The terminal covering of this device consists of lead free solder.

In case of lead free soldering, please make sure that there is no problem in practical use since there is a possibility of boundary exfoliation (Lift-off phenomenon) between the solder and the land.

REFERENCE



- 1) Unspecified tolerance shall be ± 0.2 .
- 2) Dimensions in parenthesis are shown for reference.
- 3) The deflection angle (θ) of lead terminals are $\pm 15^\circ$ MAX.
- 4) shows burr.
- 5) The mold surface other than gloss area is satin finish.
- 6) Package : Black (Visible light cut-off resin)
- 7) The lead pitch(P) is 1.27. (at lead base)

Pin name

- ① Vcc ③ GND
- ② Vo ④ GLout

Scale	Material	Finish	Name	IS471FE Outline Dimensions
5 / 1				
Unit	Lead : Fe	Lead pin : Solder dip	Drawing No.	C Y 1 2 9 6 9 L 0 2
1 = 1 / 1 mm	Package : Epoxy resin	Lead-free solder use Composition (Standard value) Sn96.5%,Ag3.0%,Cu0.5%		

REFERENCE

3. Ratings and characteristics

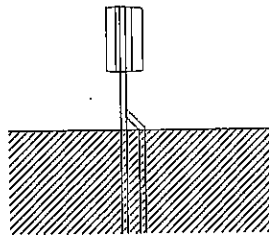
3-1 Absolute maximum ratings

Ta=25°C

Parameter	Symbol	Rating	Unit
Supply voltage	Vcc	-0.5~16	V
output	Output voltage	Vo	16
	Output current	Io	50
LED output	Output voltage	V _{GL}	16
*1 Power dissipation	P	250	mW
Operating temperature	Topr	-25 ~ +60	°C
Storage temperature	Tstg	-40 ~ +100	°C
*2 Soldering temperature	Tsol	260	°C

*1. Power dissipation vs. ambient temperature is as per fig 5.

*2. Max 5sec at the position shown below.



Solderable

Immersed to the bent angle

REFERENCE

3-2 Electro-optical characteristics

(V_{CC}=5V, T_a=25°C)

Parameter		Symbol	MIN.	TYP.	MAX.	Unit	Conditions
Supply voltage		V _{CC}	4.5	-	16	V	
Supply current		I _{CC}	-	3.5	7.0	mA	V _O , G _{LO} terminals are open.
Output	Low level output voltage	V _{OL}	-	0.15	0.35	V	I _{OL} =16mA, E _{VP} =500 lx E _{VD} =0 lx
	High level output voltage	V _{OH}	4.97	-	-	V	E _{VP} =E _{VD} =0 lx No.1
	Output short circuit current	I _{OS}	0.25	0.5	1.0	mA	E _{VP} =E _{VD} =0 lx No.1
LED Output	Low level output current	I _{GL}	40	55	70	mA	V _{GL} =1.2V
	*1 Pulse frequency	t _p	70	130	220	μs	
	*1 Pulse width	t _w	4.4	8	13.7	μs	
*2 "L→H" threshold radiation illuminance		E _{ePLH}	-	0.4	2.66	μW/mm ²	E _{eD} =0 μW/mm ² No.1,2 LED(λ _p =940nm)
*2 "H→L" threshold radiation illuminance		E _{ePHL}	-	0.7	2.8	μW/mm ²	E _{eD} =0 μW/mm ² No.1,2 LED(λ _p =940nm)
Hysteresis		E _{ePLH} /E _{ePHL}	0.45	0.65	0.95	-	
Response time	"H→L" propagation time	t _{PHL}	-	400	670	μs	No.2
	"L→H" propagation time	t _{PLH}	-	400	670		
*3 Permissible disturbance illuminance		E _{VDX}	2000	7500	-	lx	E _{eP} =7.5 μW/mm ² , λ _p =940nm

*1 The definition of Pulse frequency(t_p) and Pulse width(t_w) are shown in fig. 1.

The wave form of fig. 1 shows the output voltage wave of G_{LO} terminal of the diagram of fig. 2.

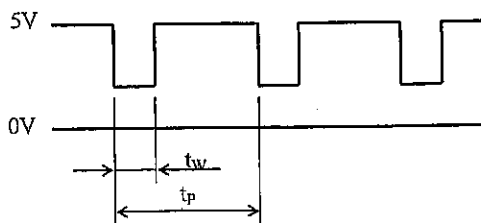


Fig.1

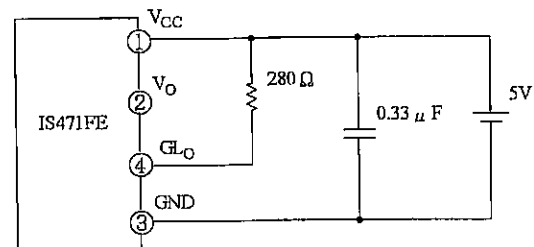


fig.2

*2 "L→H" ("H→L") threshold radiation illuminance

It shows E_{eP} when output changes to L→H (H→L).

*3 E_{VDX}: Limit of E_{VD} that this device works normally.

E_{VP} shows the illuminance of signal light synchronized with the low level timing of G_{LO} terminal output.

E_{VD} shows the illuminance of direct current light. The light source is according to CIE standard.

REFERENCE

Measurement conditions

No.1 E_{eP} , E_{eD}

E_{eP} shows the illuminance of signal light synchronized with the low level timing of GL_O terminal output.
 E_{eD} shows the illuminance of direct current light. Fig 3 shows the details.
 The light source is LED ($\lambda_p=940nm$)

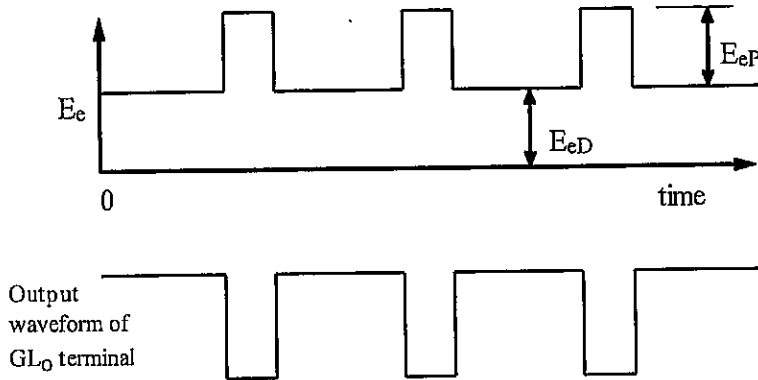


Fig.3

(Note) It shows the GL_O terminal's waveform at fig 2 diagram.

No.2 Response time, Threshold radiation illuminance

Fig 4 shows the measuring circuit of response time, threshold radiation illuminance.

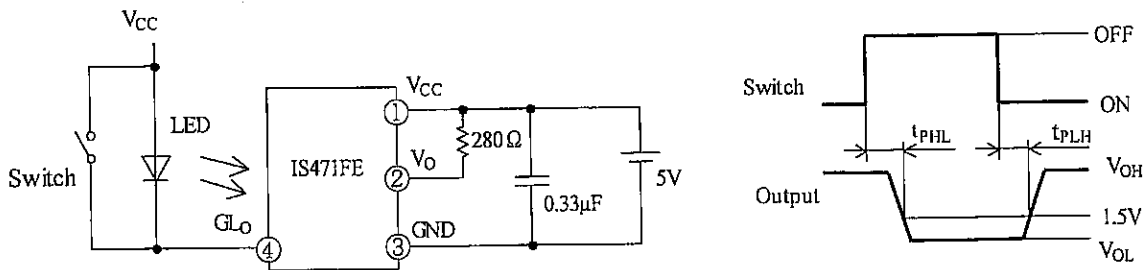
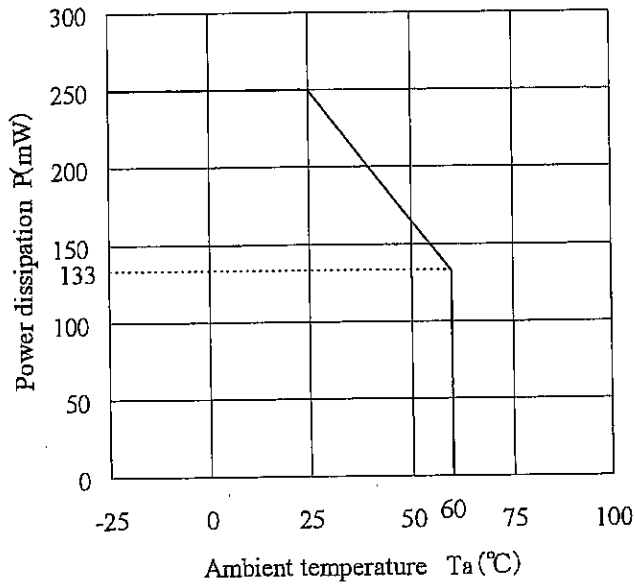


Fig.4

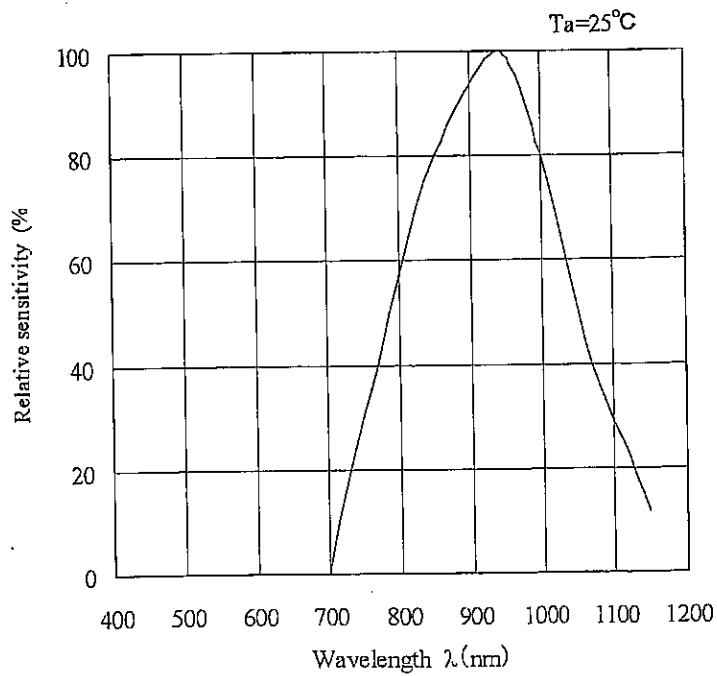
LED: peak emission wavelength $\lambda_p=940nm$.

REFERENCE

(Fig.5) Power dissipation vs. ambient temperature



(Fig.6) Spectral sensitivity (TYP)



REFERENCE

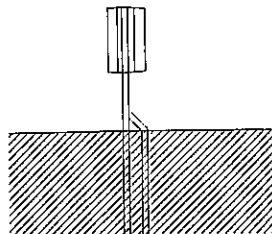
4. Reliability

The reliability of products shall satisfy items listed below.

Confidence level : 90%

LTPD : 10 or 20

Test Items	Test Conditions	Failure Judgement Criteria	Samples (n)
			Defective(C)
Temperature cycling	1 cycle -40°C ← → +100°C (20min) (20min) 20 cycles test	More than $U \times 1.2$ Less than $L \times 0.8$ U: Upper specification limit L: Lower specification limit	n=22, C=0
High temp. and high humidity storage	+60°C, 90%RH, 1000h		n=22, C=0
High temp. storage	+100°C, 1000h		n=22, C=0
Low temp. storage	-40°C, 1000h		n=22, C=0
Operation test	$V_{CC}=5V, T_a=25^\circ C, 1000h$		n=22, C=0
Mechanical shock	1000m/s ² , 6ms, Half sine wave 3 times/±X, ±Y, ±Z direction		n=11, C=0
Variable frequency vibration	100 to 2000 to 100Hz/Sweep for approx. 4min 200m/s ² , 48min/X, Y, Z direction		n=11, C=0
Electrostatic withstand voltage	±200V, 200pF Once each terminal (V _{CC} , GND reference)		n=11, C=0
Soldering heat	260±5°C , 5±0.5 s Immersed to the bent angle		n=11, C=0
Solderability	245±5°C, 5±1 s Immersed to the bent angle Flux: EC-19S (Tamura kaken corporation) No pretreatment	Solder shall adhere at less than 95% area of dipped portion.	n=11, C=0



Solderable

Immersed to the bent angle

REFERENCE

5. Outgoing inspection

(1) Inspection parameter

a. Electro-optical characteristics

Parameter		Symbol	MIN.	TYP.	MAX.	Unit	Conditions
Supply voltage		V_{CC}	4.5	-	16	V	
Supply current		I_{CC}	-	3.5	7.0	mA	V_O, GL_O terminals are open.
Output	Low level output voltage	V_{OL}	-	0.15	0.35	V	$I_{OL}=16mA, E_{VP}=500lx$ $E_{VD}=0lx$
	High level output voltage	V_{OH}	4.97	-	-	V	$E_{VP}=E_{VD}=0lx$ No.1
	Output short circuit current	I_{OS}	0.25	0.5	1.0	mA	$E_{VP}=E_{VD}=0lx$ No.1
LED Output	Low level output current	I_{GL}	40	55	70	mA	$V_{GL}=1.2V$
	* ¹ Pulse frequency	t_p	70	130	220	μs	
	* ¹ Pulse width	t_w	4.4	8	13.7	μs	
* ² "L→H" threshold radiation illuminance		E_{ePLH}	-	0.4	2.66	$\mu W/mm^2$	$E_{eD}=0\mu W/mm^2$ No.1,2 LED($\lambda_p=940nm$)
* ² "H→L" threshold radiation illuminance		E_{ePHL}	-	0.7	2.8	$\mu W/mm^2$	$E_{eD}=0\mu W/mm^2$ No.1,2 LED($\lambda_p=940nm$)
Hysteresis		E_{ePLH}/E_{ePHL}	0.45	0.65	0.95	-	
Response time	"H→L" propagation time	t_{PHL}	-	400	670	μs	No.2
	"L→H" propagation time	t_{PLH}	-	400	670		
* ³ Permissible disturbance illuminance		E_{VDX}	2000	7500	-	lx	$E_{eD}=7.5\mu W/mm^2, \lambda_p=940nm$

b. Appearance

Defects	Judgement criteria
Cracks of product (resin area)	The cracks above 1mm size, and cracks over the lead frame are defects.

* The appearance should not affect the electrical, optical characteristics.

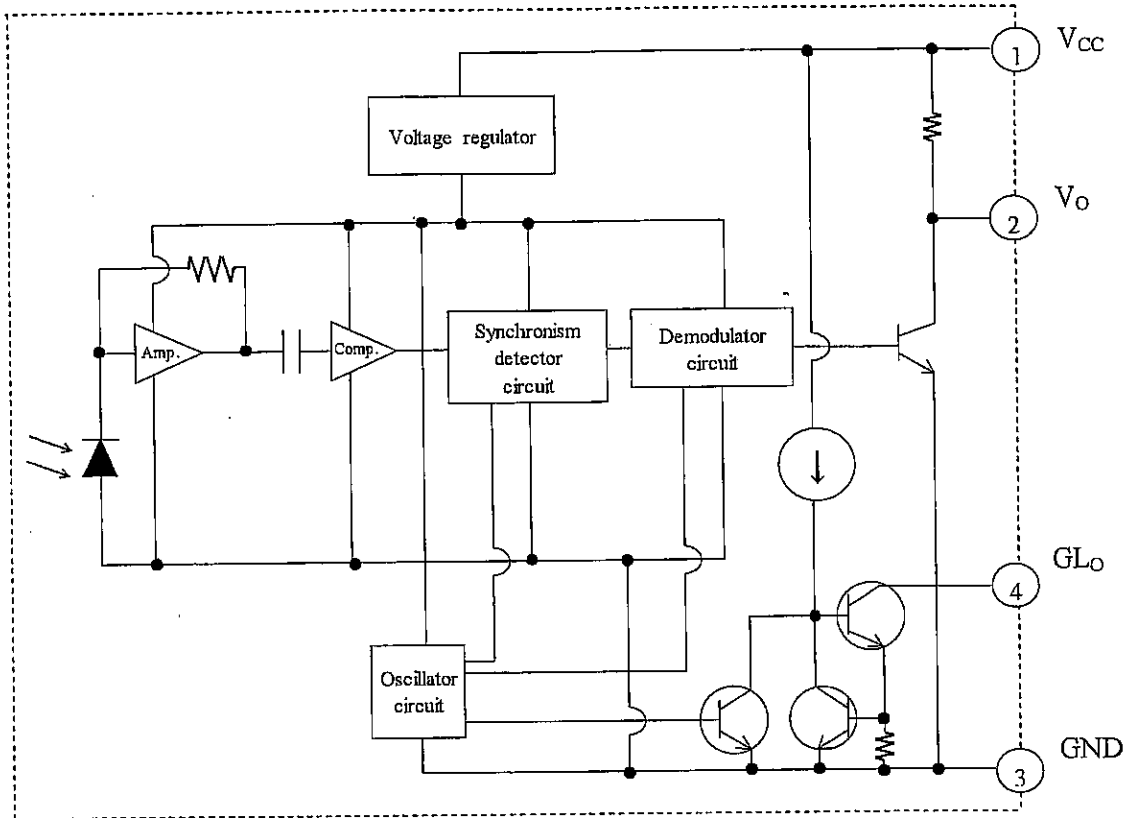
(2) Sampling method and inspection criteria

ISO 2859 one time sampling

Defects	Judgement criteria	AQL(%)
Major defects (Electro-optical characteristics defects, Assembly defects)	Normal inspection level II	0.1
Minor defects (Appearance defects)	Normal inspection level II	0.25

REFERENCE

6-1 Equivalent circuit and Operating
(6-1-1) Equivalent circuit



(6-1-2) Operating (True value)

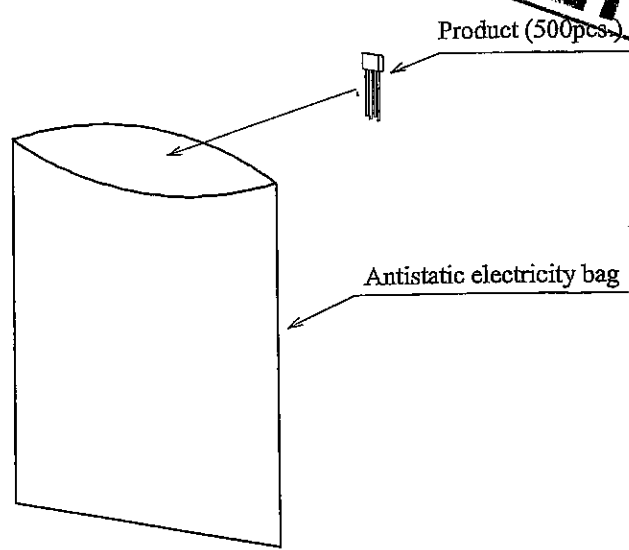
Input	Output
Light ON	Low level
Light OFF	High level

REFERENCE

6-2 Packaging

6-2-1 Inner packing

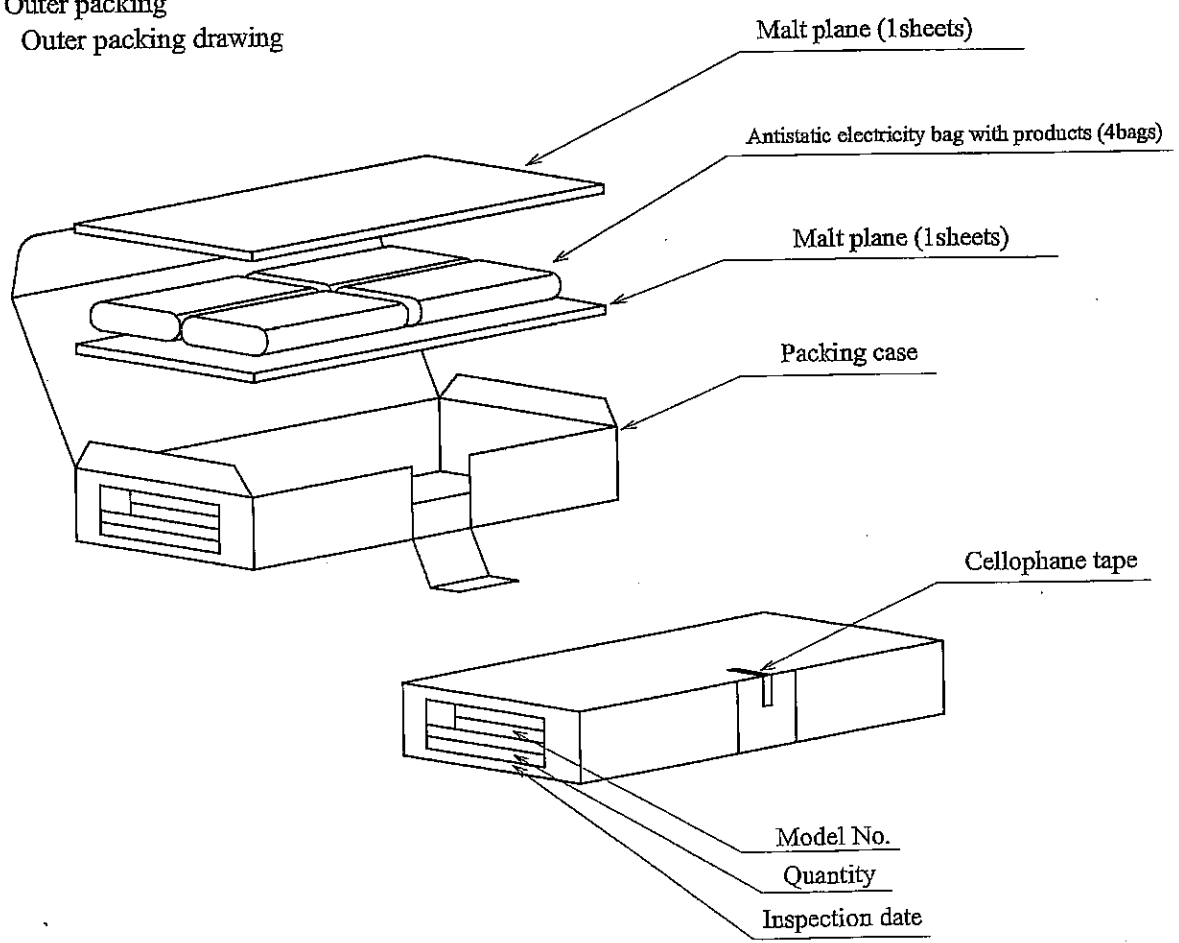
① Inner packing drawing



- ② Inner packing material : Antistatic electricity bag (Polyethylene)
- ③ Quantity : 500pcs./bag

6-2-2 Outer packing

① Outer packing drawing



- ② Outer material : Packing case (Corrugated cardboard), Malt plane (Urethane), Cellophane tape
- ③ Quantity : 2000pcs./box
- ④ Indication : Model No., quantity and inspection date
- ⑤ Regular packaged mass : Approximately 430g

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9